



Integrated Device Technology, Inc.

**4K x 36 BiCMOS
SYNCHRONOUS DUAL-PORT
STATIC RAM MODULE**

**PRELIMINARY
IDT7M1024**

FEATURES:

- High-density 4K x 36 Synchronous Dual-Port SRAM module
- Architecture based on Dual-Port RAM cells
 - Allows full simultaneous access from both ports
- Synchronous operation
 - 4ns set-up to clock, 1ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 15ns clock to data out
 - Self-timed write allows fast write cycle
- Clock enable feature
- Single 5V (±10%) power supply
- Multiple GND pins and decoupling capacitors for maximum noise immunity
- Inputs/outputs directly TTL-compatible

ramic substrate using four IDT7099 (4K x 9) Dual-Port RAMs. The IDT7M1024 module is designed to be used as a stand-alone 36-bit Dual-Port Static RAM.

The IDT7M1024 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide very short set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal. An asynchronous output enable is provided to ease asynchronous bus interfacing.

The internal write pulse width is independent of the HIGH and LOW periods of the clock. This allows the shortest possible realized cycle times. Clock enable inputs are provided to stall the operation of the address and data input registers without introducing clockskew for very fast interleaved memory applications.

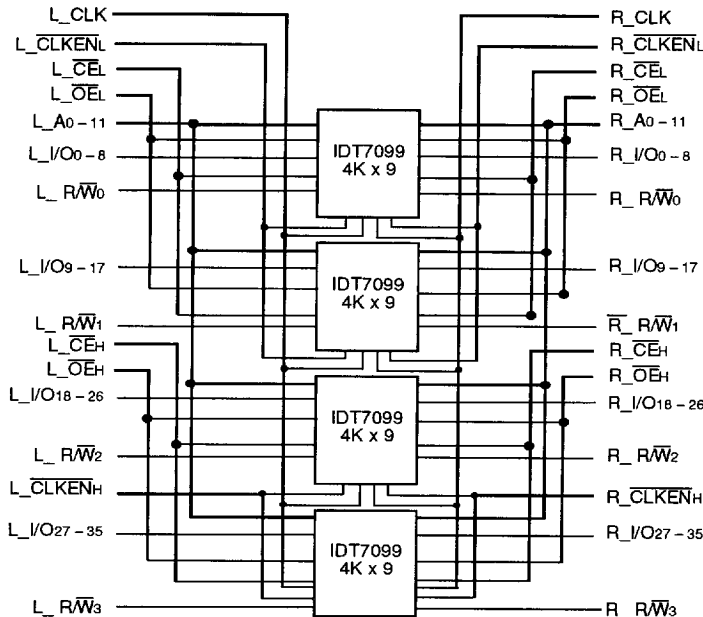
The data inputs are gated to control on-chip noise in bussed applications. The user must guarantee that the R/W pins are LOW for at least one clock cycle before any write is attempted. A HIGH on the \overline{CE} input for one clock cycle will power down the internal circuitry to reduce static power consumption.

The IDT7M1024 module is packaged in a 142-lead ceramic

DESCRIPTION:

The IDT7M1024 is a 4K x 36 bit high-speed synchronous Dual-Port Static RAM module constructed on a co-fired ce-

FUNCTIONAL BLOCK DIAGRAM



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MILITARY AND COMMERCIAL TEMPERATURE RANGES

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DSC-7087/3

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PGA (Pin Grid Array).

All IDT military modules are constructed with semiconductor components manufactured in compliance with the latest revision of MIL-STD-883, Class B making them ideally suited to applications demanding the highest level of performance and reliability.

PIN CONFIGURATION

	1	2	3	4	5	6	7	8	9	10	11	12	13
A	GND	L_I/O3	L_I/O2	GND	L_I/O1	L_I/O0	GND	R_I/O0	R_I/O1	GND	R_I/O2	R_I/O3	GND
B	L_I/O4	L_I/O5	L_I/O6	L_A2	L_A1	L_A0	L_CLK	R_A0	R_A1	R_A2	R_I/O6	R_I/O5	R_I/O4
C	L_I/O8	VCC	L_I/O7	GND	L_CLKEN L	L_CLKEN H	R_CLK	R_CLKEN H	R_CLKEN L	GND	R_I/O7	VCC	R_I/O8
D	L_I/O9	L_I/O10	L_I/O11	L_A3	GND			GND	R_A3	R_A4	R_I/O11	R_I/O10	R_I/O9
E	L_I/O12	L_OE L	L_OE H	L_A4						R_A5	R_OE H	R_OE L	R_I/O12
F	L_I/O13	L_OE L	L_OE H	L_A5						R_A6	R_OE H	R_OE L	R_I/O13
G	GND	L_R/W0	L_R/W1	GND						GND	R_R/W1	R_R/W0	GND
H	L_I/O14	L_R/W2	L_R/W3	L_A6						R_A7	R_R/W3	R_R/W2	R_I/O14
J	L_I/O15	L_I/O16	L_I/O17	L_A7						R_A8	R_I/O17	R_I/O16	R_I/O15
K	L_I/O20	L_I/O19	L_I/O18	GND	L_A10	L_A11	GND	R_A11	R_A10	GND	R_I/O18	R_I/O19	R_I/O20
L	L_I/O21	VCC	L_I/O22	L_A8	L_A9	L_I/O31	R_I/O35	R_I/O34	R_I/O30	R_A9	R_I/O22	VCC	R_I/O21
M	L_I/O23	L_I/O24	L_I/O25	L_I/O29	L_I/O30	L_I/O32	L_I/O35	R_I/O33	R_I/O31	R_I/O29	R_I/O25	R_I/O24	R_I/O23
N	GND	L_I/O26	L_I/O27	L_I/O28	GND	L_I/O33	L_I/O34	R_I/O32	GND	R_I/O28	R_I/O27	R_I/O26	GND

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PIN NAMES

Left Port	Right Port	Names
L_R/W 0-3	R_R/W 0-3	Byte Read/Write Enables
L_OE L,H	R_OE L,H	Word Output Enables
L_CE L,H	R_CE L,H	Word Chip Enables
L_CLKEN L,H	R_CLKEN L,H	Word Clock Enables
L_CLK	R_CLK	Clock Inputs
L_A 0-11	R_A 0-11	Address Inputs
L_I/O 0-35	R_I/O 0-35	Data Input/Outputs
VCC		Power
GND		Ground

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Commercial	Military	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
VTERM ⁽³⁾	Terminal Voltage	-0.5 to Vcc	-0.5 to Vcc	V
TA	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
TSTG	Storage Temperature	-55 to +125	-65 to +150	°C
IOUT	DC Output Current	50	50	mA

- NOTES:**
- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
 - Inputs and Vcc terminals only.

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Ambient Temperature	GND	VCC
Military	-55°C to +125°C	0V	5.0V ± 10%
Commercial	0°C to +70°C	0V	5.0V ± 10%

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RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
VIH	Input HIGH Voltage	2.2	—	6.0	V
VIL	Input LOW Voltage	-0.5 ⁽¹⁾	—	0.8	V

- NOTE:**
- VIL = -3.0V for pulse width less than 20ns.

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CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Condition	Max.	Unit
CIN	Input Capacitance	VIN = 0V	50	pF
COU	Output Capacitance	VOUT = 0V	15	pF

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TRUTH TABLES

TRUTH TABLE I: READ/WRITE CONTROL⁽¹⁾

Inputs				Outputs	Mode
Synchronous		Asynchronous			
Clk	OE	R/W	OE	I/O-ss	
/	h	h	X	High-Z	Deselected, Power Down, Data I/O Disabled
/	h	l	X	DATAIN	Deselected, Power Down, Data Input Enabled
/	l	l	X	DATAIN	Write
/	l	h	L	DATAOUT	Read
/	l	h	H	High-Z	Data I/O Disabled

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TRUTH TABLE II: CLOCK ENABLE FUNCTION TABLE⁽¹⁾

Operating Mode	Inputs		Register Inputs		Register Outputs	
	Clk	CLKEN	ADDR	DATAIN	ADDR	DATAOUT
Load "1"	/	l	h	h	H	H
Load "0"	/	l	l	l	L	L
Hold (do nothing)	/	h	X	X	N/C	N/C
	X	H	X	X	N/C	N/C

- NOTE:**
- H = HIGH voltage level steady state, h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition, L = LOW voltage level steady state, l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition, X = Don't care, N/C = No change

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DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE ($V_{CC} = 5.0V \pm 10\%$) **INTEGRATED DEVICE**

Symbol	Parameter	Test Condition	IDT7M1024		Unit
			Min.	Max.	
I _{LI}	Input Leakage Current	$V_{CC} = 5.5V, V_{IN} = 0V \text{ to } V_{CC}$	—	40	μA
I _{LO}	Output Leakage Current	$\overline{CE} = V_{IH}, V_{OUT} = 0V \text{ to } V_{CC}$	—	10	μA
V _{OL}	Output LOW Voltage	I _{OL} = 4mA	—	0.4	V
V _{OH}	Output HIGH Voltage	I _{OH} = -4mA	2.4	—	V

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DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE ($V_{CC} = 5V \pm 10\%$)

Symbol	Parameter	Test Condition	Version	IDT7M1024SxxG, IDT7M1024SxxGB								Unit
				-15 ⁽¹⁾		-20		-25		-30		
				Typ.	Max.	Typ.	Max.	Typ.	Max.	Typ.	Max.	
I _{CC}	Dynamic Operating Current (Both Ports Active)	$\overline{CE} \leq V_{IL}$ Outputs Open $f = f_{MAX}^{(2)}$	Mil	—	—	—	1560	—	1480	—	1440	mA
			Com'l	—	1560	—	1440	—	1360	—	1360	
I _{SB1}	Standby Current (Both Ports—TTL Level Inputs)	$L_{\overline{CE}}$ and $R_{\overline{CE}} \geq V_{IH}$ $f = f_{MAX}^{(2)}$	Mil	—	—	—	760	—	680	—	560	mA
			Com'l	—	880	—	720	—	640	—	560	
I _{SB2}	Standby Current (One Port—TTL Level Inputs)	$L_{\overline{CE}}$ or $R_{\overline{CE}} \geq V_{IH}$ Active Port Outputs Open, $f = f_{MAX}^{(2)}$	Mil	—	—	—	1160	—	1080	—	1000	mA
			Com'l	—	1200	—	1080	—	1000	—	1000	
I _{SB3}	Full Standby Current (Both Ports—CMOS Level Inputs)	Both Ports $R_{\overline{CE}}$ and $L_{\overline{CE}} \geq V_{CC} - 0.2V$ $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V, f = 0^{(3)}$	Mil	—	—	—	80	—	80	—	80	mA
			Com'l	—	40	—	40	—	40	—	40	
I _{SB4}	Full Standby Current (One Port—CMOS Level Inputs)	One Port $L_{\overline{CE}}$ or $R_{\overline{CE}} \geq V_{CC} - 0.2V, V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V, \text{Active Port}$ Outputs Open, $f = f_{MAX}^{(2)}$	Mil	—	—	—	1120	—	1040	—	960	mA
			Com'l	—	1160	—	1040	—	960	—	960	

NOTES:

- 0°C to +70°C temperature range only
- At $f = f_{MAX}$, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/CLK, and using "AC TEST CONDITIONS" of input levels of GND to 3V
- $f = 0$ means no address, clock, or control lines change. Applies only to inputs at CMOS level standby

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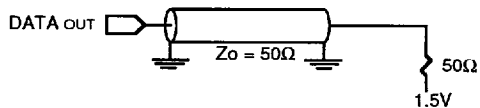
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AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1, 2 and 3

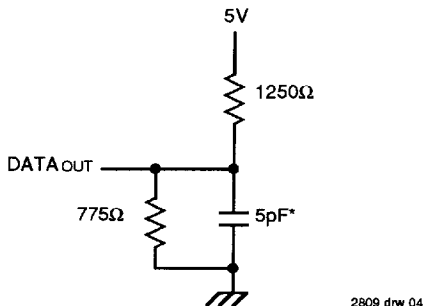
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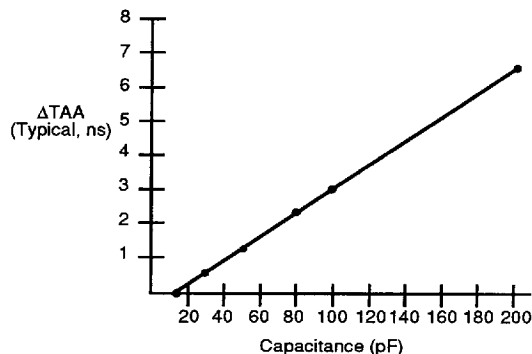
Figure 1. Output Load



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Figure 2. Output Load (for tCLZ, tCHZ, tOLZ, and tOHZ)

*Including scope and jig.



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Figure 3. Lumped Capacitive Load, Typical Derating

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE RANGE — (READ AND WRITE CYCLE TIMING)

(Commercial: Vcc = 5V ± 10%, TA = 0°C to +70°C; Military: Vcc = 5V ± 10%, TA = -55°C to +125°C)

Symbol	Parameter	7M1024SxxG, 7M1024SxxGB				Unit				
		-15 ⁽¹⁾		-20			-25		-30	
		Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
tCLK	Clock Cycle Time	15	—	20	—	25	—	30	—	ns
tCLKH	Clock HIGH Time	6	—	8	—	10	—	12	—	ns
tCLKL	Clock LOW Time	6	—	8	—	10	—	12	—	ns
tCQV	Clock HIGH to Output Valid	—	15	—	20	—	25	—	30	ns
tRSU	Registered Signal Set-up Time	4	—	5	—	6	—	7	—	ns
tRHD	Registered Signal Hold Time	1	—	2	—	2	—	2	—	ns
tCOH	Data Output Hold After Clock HIGH	3	—	3	—	3	—	3	—	ns
tCLZ	Clock HIGH to Output Low-Z	2	—	2	—	2	—	2	—	ns
tCHZ	Clock HIGH to Output High-Z	2	7	9	2	12	2	15	ns	
tOE	Output Enable to Output Valid	—	8	—	10	—	12	—	15	ns
tOLZ	Output Enable to Output Low-Z	0	—	0	—	0	—	0	—	ns
tOHZ	Output Disable to Output High-Z	—	7	—	9	—	11	—	14	ns
tCSU	Clock Enable, Disable Set-up Time	4	—	5	—	6	—	7	—	ns
tCHD	Clock Enable, Disable Hold Time	2	—	3	—	3	—	3	—	ns
Port-to-Port Delay										
tCWDD	Write Port Clock HIGH to Read Data Delay	—	30	—	35	—	45	—	55	ns

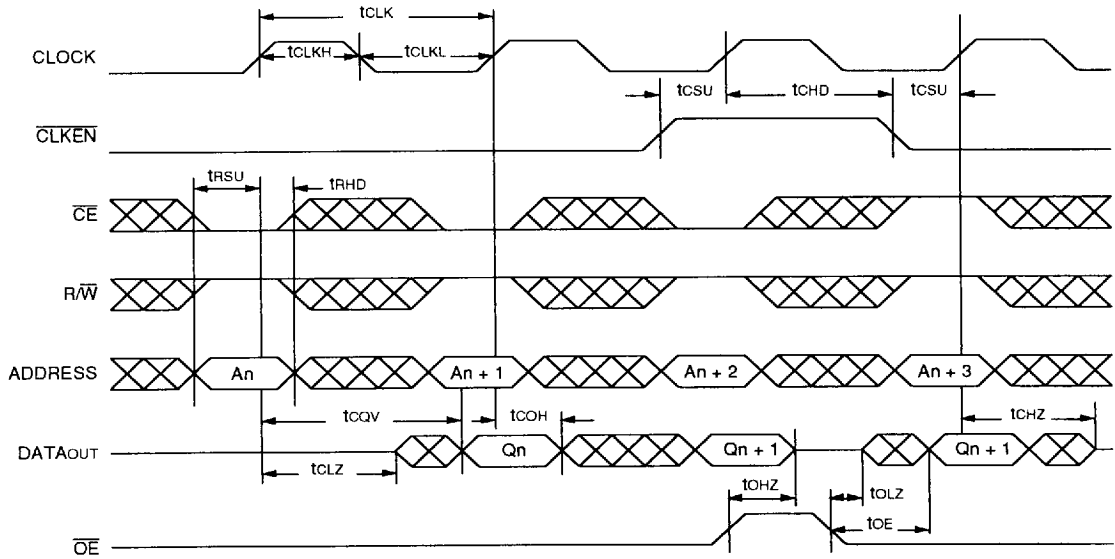
NOTE:

1. 0°C to +70°C temperature range only.

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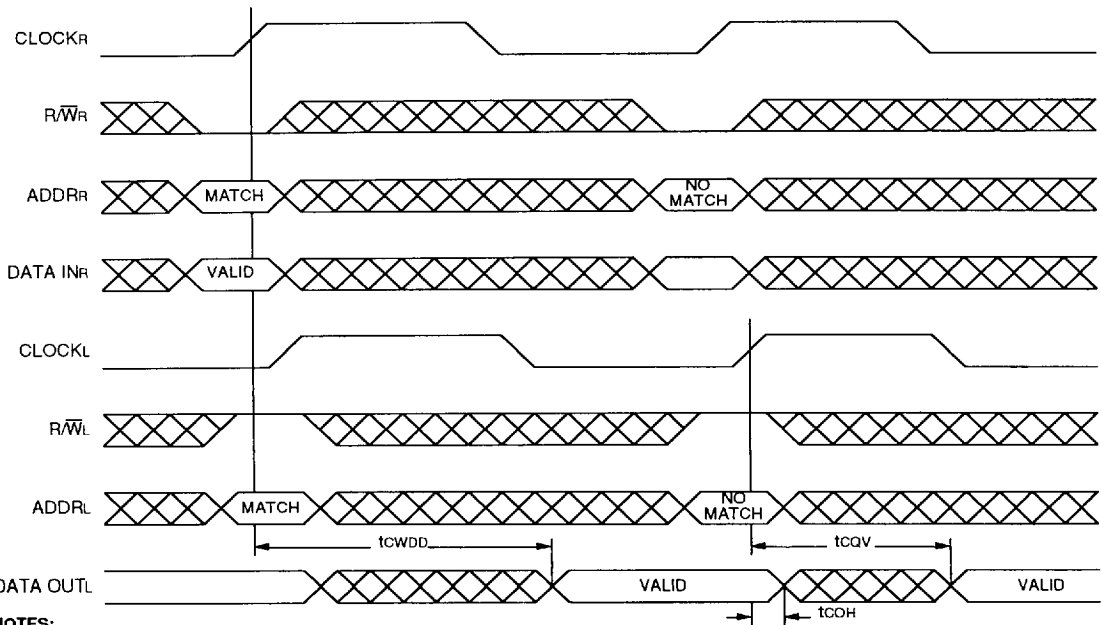
TIMING WAVEFORM OF READ CYCLE, EITHER SIDE^(1,2)

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TIMING WAVEFORM OF READ CYCLE WITH PORT-TO-PORT DELAY

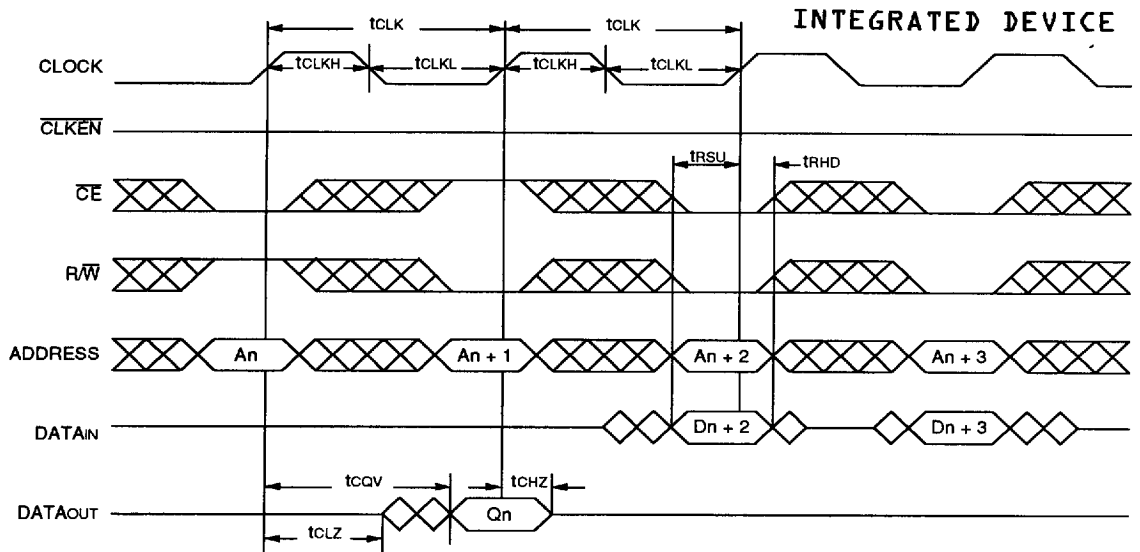


- NOTES:
1 L $\overline{CE} = R_{\overline{CE}} = L$, L $\overline{CLKEN} = R_{\overline{CLKEN}} = L$
2 $\overline{OE} = L$ for the reading port

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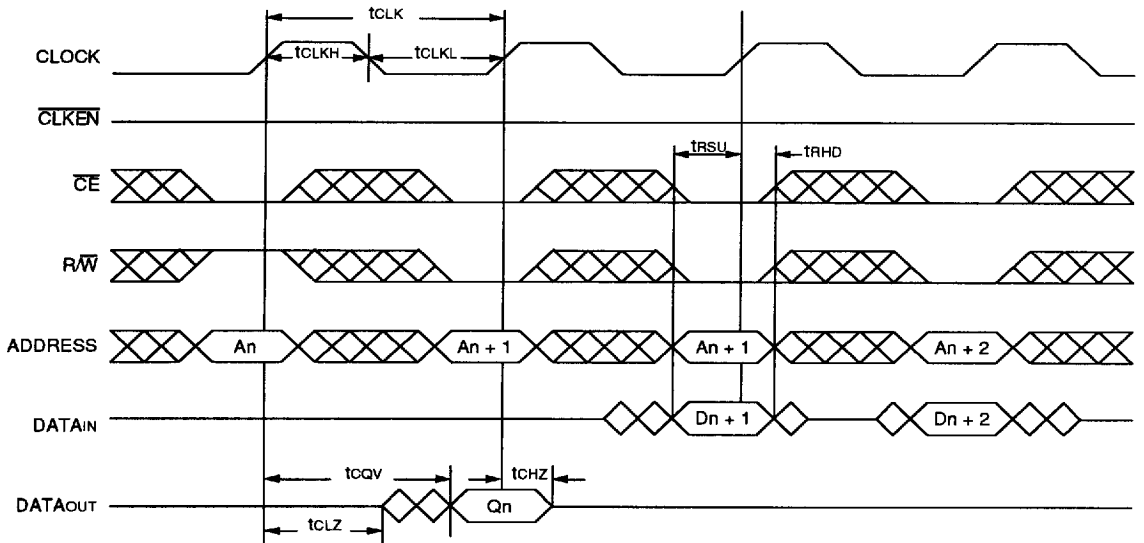
TIMING WAVEFORM OF READ-TO-WRITE CYCLE No. 1, CE HIGH⁽¹⁾



NOTE:
1. \overline{CE} LOW throughout.

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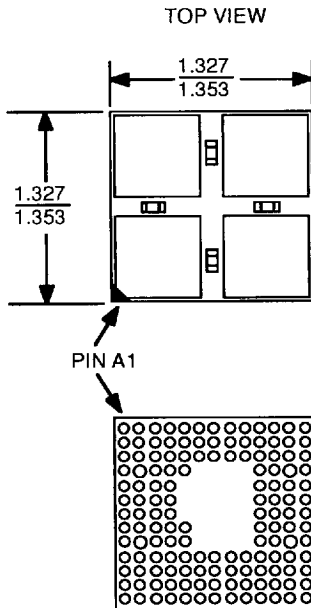
TIMING WAVEFORM OF READ-TO-WRITE CYCLE NO. 1, \overline{CE} LOW^(1,2)



NOTES:
1. During dead cycle, if \overline{CE} is LOW, data will be written into array.
2. \overline{CE} LOW throughout.

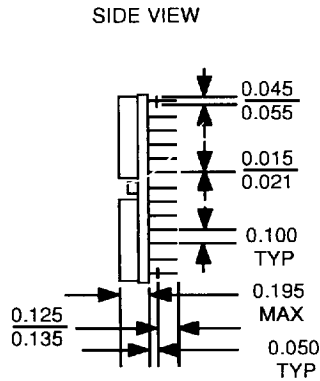
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PACKAGE DIMENSIONS



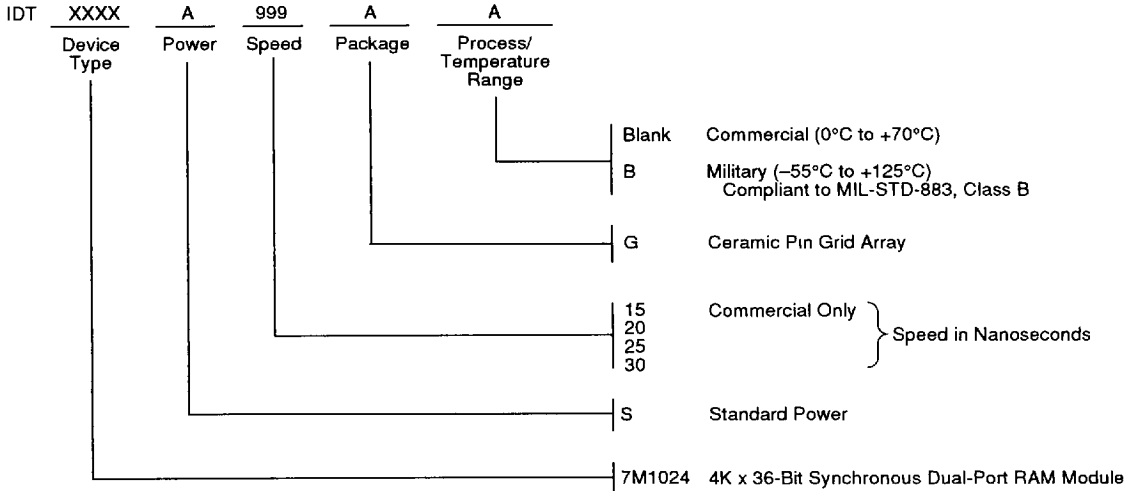
BOTTOM VIEW

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ORDERING INFORMATION



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